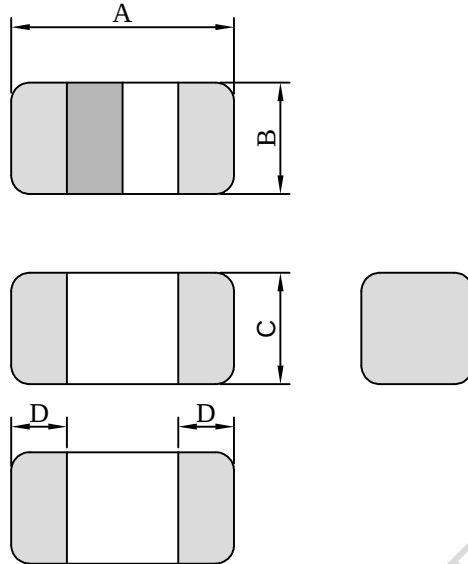


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1005□□□□C□-□□□		
		REV.	20240815	PAGE	1	

I . Configuration and dimensions :



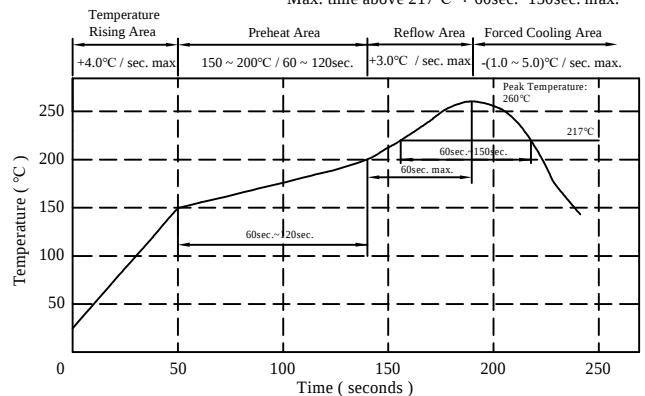
Unit : mm

A	B	C	D
1.00 ±0.15	0.50 ±0.15	0.50 ±0.15	0.25 ±0.10

II . Description :

- a . Body : Ceramic
- b . Inner electrode : Silver
- c . Terminal electrode : Ag / Ni / Sn
- d . Product weight : 0.8 mg (ref.)
- e . Products comply with RoHS' requirements
- f . Halogen free

Peak temp. : 260°C max.
Max. peak temp. - 5°C : 30sec. max.
Max. time above 217°C : 60sec.~150sec. max.



III . General specification :

- a . Operating temp. : -40°C----+125°C
(Temp. rise included)
- b . Resistance to solder heat : 260°C . 10 sec.

AR-001C



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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1005□□□□C□-□□□		
		REV.	20240815	PAGE	2	

IV . Electrical characteristics :

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz) L&Q	SRF (MHz) min.	RDC (Ω) max.	IDC (mA) max.
EDP10051N0□CB-□□□	1.000	B,C,S	8	100M /50mV	10000	0.060	1000
EDP10051N1□CB-□□□	1.100	B,C,S	8	100M /50mV	10000	0.070	1000
EDP10051N2□CB-□□□	1.200	B,C,S	8	100M /50mV	10000	0.070	1000
EDP10051N3□CB-□□□	1.300	B,C,S	8	100M /50mV	10000	0.070	1000
EDP10051N5□CB-□□□	1.500	B,C,S	8	100M /50mV	6000	0.080	1000
EDP10051N6□CB-□□□	1.600	B,C,S	8	100M /50mV	6000	0.080	1000
EDP10051N8□CB-□□□	1.800	B,C,S	8	100M /50mV	6000	0.080	900
EDP10052N0□CB-□□□	2.000	B,C,S	8	100M /50mV	6000	0.090	900
EDP10052N2□CB-□□□	2.200	B,C,S	8	100M /50mV	6000	0.090	900
EDP10052N4□CB-□□□	2.400	B,C,S	8	100M /50mV	6000	0.100	800
EDP10052N7□CB-□□□	2.700	B,C,S	8	100M /50mV	6000	0.120	800
EDP10053N0□CB-□□□	3.000	B,C,S	8	100M /50mV	6000	0.120	800
EDP10053N3□CB-□□□	3.300	B,C,S	8	100M /50mV	6000	0.130	800
EDP10053N6□CB-□□□	3.600	B,C,S	8	100M /50mV	4000	0.150	700
EDP10053N9□CB-□□□	3.900	B,C,S	8	100M /50mV	4000	0.160	700
EDP10054N3□CB-□□□	4.300	B,C,S	8	100M /50mV	4000	0.160	700
EDP10054N7□CB-□□□	4.700	B,C,S	8	100M /50mV	4000	0.160	700
EDP10055N1□CB-□□□	5.100	B,C,S	8	100M /50mV	4000	0.160	600
EDP10055N6□CB-□□□	5.600	B,C,S	8	100M /50mV	4000	0.200	600
EDP10056N2□CB-□□□	6.200	B,C,S	8	100M /50mV	3900	0.200	600
EDP10056N8□CB-□□□	6.800	H,J	8	100M /50mV	3900	0.200	600
EDP10057N5□CB-□□□	7.500	H,J	8	100M /50mV	3700	0.240	500
EDP10058N2□CB-□□□	8.200	H,J	8	100M /50mV	3600	0.240	500
EDP10059N1□CB-□□□	9.100	H,J	8	100M /50mV	3400	0.260	500
EDP100510N□CB-□□□	10.00	H,J	8	100M /50mV	3200	0.260	500
EDP100512N□CB-□□□	12.00	H,J	8	100M /50mV	2700	0.500	400
EDP100515N□CB-□□□	15.00	H,J	8	100M /50mV	2300	0.500	400
EDP100518N□CB-□□□	18.00	H,J	8	100M /50mV	2100	0.600	350
EDP100520N□CB-□□□	20.00	H,J	8	100M /50mV	2000	0.600	350
EDP100522N□CB-□□□	22.00	H,J	8	100M /50mV	1900	0.600	350
EDP100527N□CB-□□□	27.00	H,J	8	100M /50mV	1600	0.700	300
EDP100533N□CB-□□□	33.00	H,J	8	100M /50mV	1300	0.800	300
EDP100539N□CB-□□□	39.00	H,J	8	100M /50mV	1200	1.000	250
EDP100543N□CB-□□□	43.00	H,J	8	100M /50mV	1100	1.100	250
EDP100547N□CB-□□□	47.00	H,J	8	100M /50mV	1000	1.100	250
EDP100556N□CB-□□□	56.00	H,J	8	100M /50mV	750	1.200	200
EDP100568N□CB-□□□	68.00	H,J	8	100M /50mV	750	1.400	200
EDP100582N□CB-□□□	82.00	H,J	8	100M /50mV	750	1.600	200

AR-001C



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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1005□□□□C□-□□□		
		REV.	20240815	PAGE	2-1	

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz) L&Q	SRF (MHz) min.	RDC (Ω) max.	IDC (mA) max.
EDP1005R10□CB-□□□	100.0	H,J	8	100M /50mV	700	2.000	200
EDP1005R12□CB-□□□	120.0	H,J	8	100M /50mV	600	2.500	150
EDP1005R15□CB-□□□	150.0	H,J	8	100M /50mV	550	3.000	150
EDP1005R18□CB-□□□	180.0	H,J	8	100M /50mV	500	3.500	150
EDP1005R22□CB-□□□	220.0	H,J	8	100M /50mV	450	3.700	100
EDP1005R27□CB-□□□	270.0	H,J	8	100M /50mV	400	4.500	100
EDP1005R33□CB-□□□	330.0	H,J	6	50M /50mV	350	5.000	80
EDP1005R36□CB-□□□	360.0	H,J	6	50M /50mV	300	6.000	80

- 1). Electrical specifications at 25°C
- 2). IDC base on temp. rise 40°C max.
- 3). □ Represents inductance tolerance : $L_s < 6.8\text{nH}$, □ Please select“B/C/S” level ;
 $L_s \geq 6.8\text{nH}$, □ Please select “H/J” level ;
- 4). Tolerance : B($\pm 0.1\text{nH}$) 、 C($\pm 0.2\text{nH}$) 、 S($\pm 0.3\text{nH}$) 、 H($\pm 3\%$) 、 J($\pm 5\%$)

AR-001C



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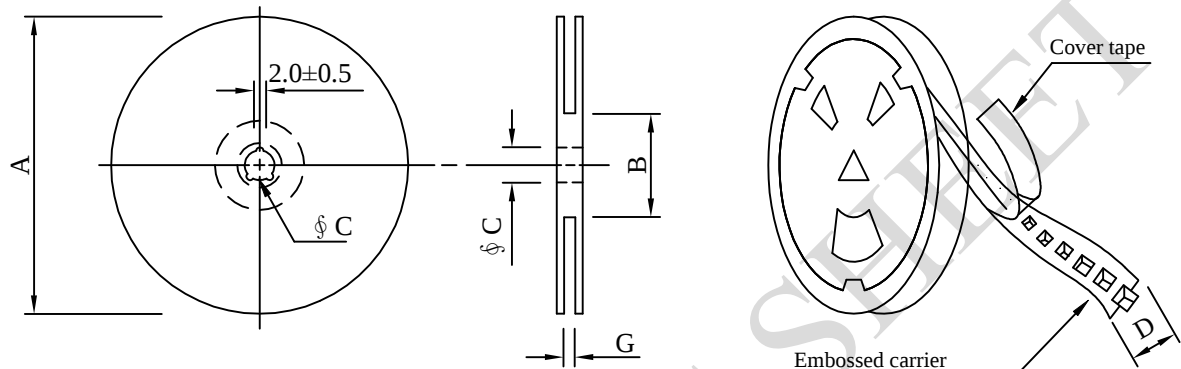
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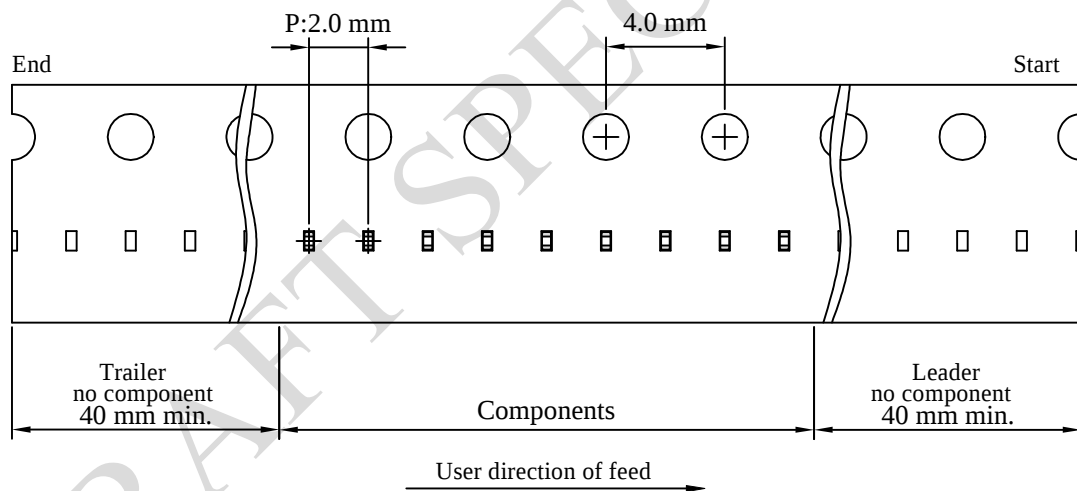
PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1005□□□□C□-□□□		
		REV.	20240815	PAGE	3	

V . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:mm

Style	A	B	C	D	G
07 - 08	178±2.0	57±2.0	12.5±1.5	8	8.0 ^{+1.50} _{-0.00}

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	10,000	135	07 - 08	500,000	8.20	39 x 31 x 39

AR-001C



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ABC-ATEC ELECTRONICS GROUP

SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1005□□□□C□-□□□		
		REV.	20240815	PAGE	4	

VI . Drawing number expression :

E

D

P

1

0

0

5

C

—

Reference code

Appendix code 2 : Package

Appendix code 1 : Classification

Tolerance code

Electrical code

Dimension code

Type code

Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T /R (Reel package)	NA	NA	NA	10,000 pcs	

AR-001C



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ABC-ATEC ELECTRONICS GROUP

SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Chip High Frequency Inductor	ABC'S DWG NO.		EDP1005□□□□C□-□□□	
		REV.	20240815	PAGE	5

VII . Safety notes :

1. Products do not be used in related applications that directly affect the personal safety system or cause significant impacts and losses on society. If you apply to these applications, please be sure to contact us at first to confirm.
產品不可使用於直接影響人身安全系統或對社會會造成重大影響與損失之相關用途，若您應用於此，請務必優先與我們聯繫確認。
2. The storage period is less than 12 months. Ensure to follow the storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 60% RH or less). If the storage time is exceeded the limit, the electrodes might be deteriorate of terminal soldering.
儲存期不超過12個月，務必遵守儲存條件（溫度：5至30°C，濕度：10至60%RH以下）。如果超過了儲存時間，端子電極可能會氧化而影響焊接。
3. Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
不要在有氣體腐蝕等條件的地方使用或存放（鹽，酸，鹼等）。
4. Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
安裝時的焊接條件應在規格範圍內。如果超過要求，可能會發生短路，性能下降或壽命縮短。
5. When using, it should try to avoid excessive mechanical impact on the product, such as collision / drop ... and other reasons.
使用時，應盡量避免產品受到過度機械衝擊，如碰撞/掉落...等原因。
6. When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.
將已安裝新片的電路板組裝到裝置時，請注意應盡量避免電路板受到組裝變形...等，導致產品受到應力。
7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
產品會因通電而自我發熱(溫度上升)，因此在熱影響設計方面，需保留適當公差。
8. Do not expose the products to magnets or magnetic fields.
請勿將產品暴露於磁鐵或是磁場中。
9. If you would like to use this products to performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property, or if you have special requirements exceeding the range or conditions set forth in the each catalog, please contact us.
如果您希望將此產品用於性能和/或質量要求更嚴格的安全性或可靠性，或其失敗、故障或麻煩可能對社會、個人或財產造成嚴重損害，或者您有特殊情況要求超出目錄中規定的範圍或條件，請與我們聯繫。